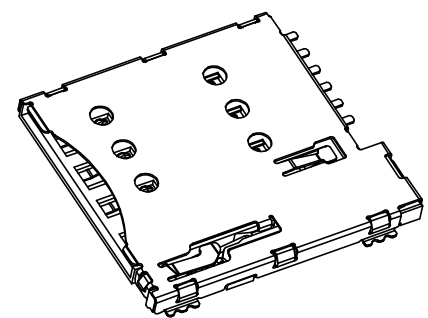
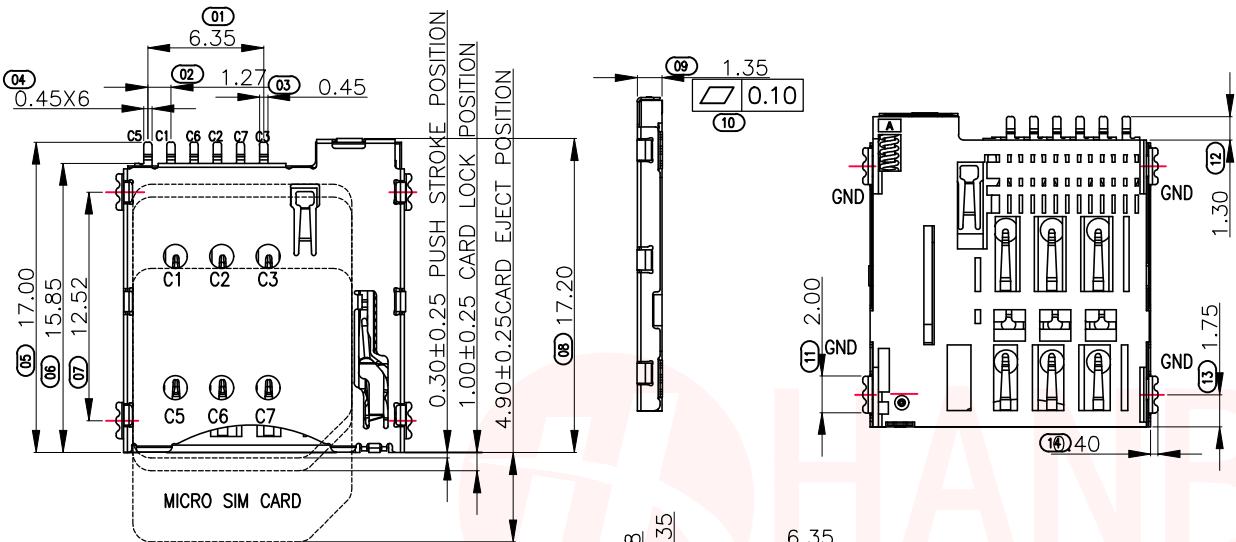




REV.	ECN NO OR DESCRIPTION	REVISED	DATE

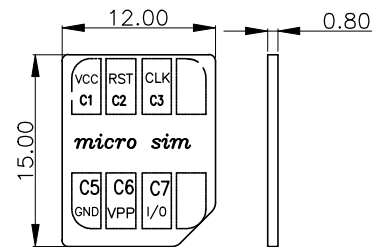
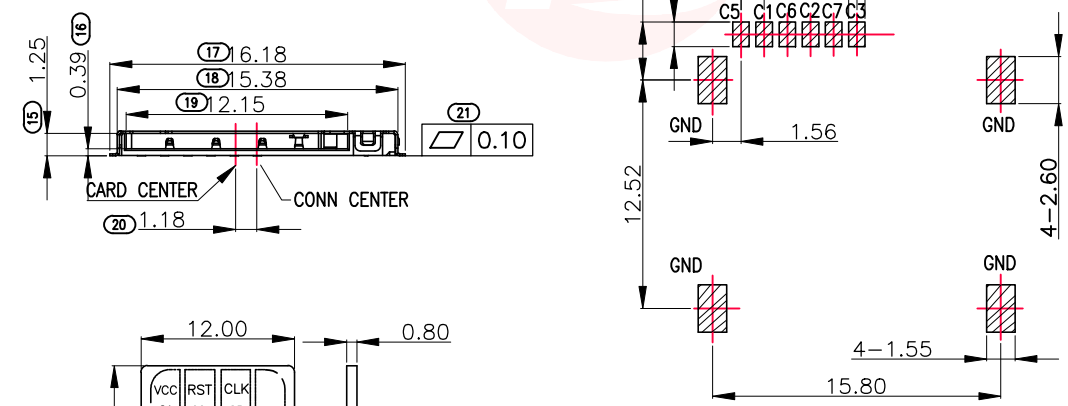


NOTES:
MATERIAL:
Insulator: High Temperature Thermoplastic,
Contact: Copper Alloy
Shell: STAINLESS

PLATING:
Contact: Plated 30u" Ni Overall ,Solder Area: Tin,Contact G/F
Shell: Plated 30u" Ni Overall
Plated G/F Selective Contact Area

Electrical:
Current Rating :0.5A AC/DC max.
Voltage Rating :50V AC/DC MAX
Ambient Temperature Range :-20°C~+85°C
Storage Temperature Range :-40°C~+70°C
Ambient Humidity Range :95% R.H. Max.
Contact Resistance:100mΩ max.
Insulation Resistance:1000M min./250V DC
Dielectric Withstanding Voltage:500V AC
Mating Cycles:5,000 Insertions
Temperature: 260°C ±5°

SIM pin Assignment	
PIN#	Name
C1	VCC
C2	RST
C3	CLK
C5	GND
C6	VPP
C7	I/O



■ CIRCUIT TRACE KEEP OUT AREA
■ SMT SOLDER AREA

THERE SHOULD NOT BE ANY CIRCUITRIES IN THE LAYOUT SPACE OF THE PRODUCTS.

RECOMMENDED PCB LAYOUT
GENERAL TOLERANCE ±0.05

UNLESS OTHERWISE SPECIFIED TOLERANCES

DECIMALS:	ANGLES:
X :±0.30	X :±2°
X.X :±0.20	X.X :±1°
X.XX :±0.10	

东莞市汉博电子科技有限公司
DONGGUAN HANBO TECHNOLOGY CO., LTD

TITLE	6PIN 1.35H PUSH PUSH MICRO SIM CARD 无侦测			
DWN	xiong	PART NO. SM0-222-P6		
CHKD	lee	SCALE:1:1	UNIT: mm	
APVD	wang	SIZE: A4	SHEET:10F 1	REV: A4
CUSTOMER COPY				